



Surface Mount Attenuator 10 Watts, 20dB

The XRA10AA20SES is a high performance Aluminum Nitride (AlN) chip attenuator intended as a cost competitive alternative to Beryllium Oxide (BeO). It is designed particularly for LTE and 5G wireless communication frequency bands. The high power handling makes the part ideal for inter-stage matching, directional couplers, and for use in isolators. The attenuator is also RoHS compliant!

Features:

- RoHS Compliant
- 10 Watts
- Low Cost
- DC – 6.0GHz
- AlN Ceramic
- Non-Nichrome Resistive Element
- Low VSWR
- 100% Tested

General Specifications

Resistive Element	Thick film
Substrate	AlN Ceramic
Terminal Finish	Matte Tin over Nickel Barrier
Operating Temperature	-55 to +150°C (see de-rating chart)

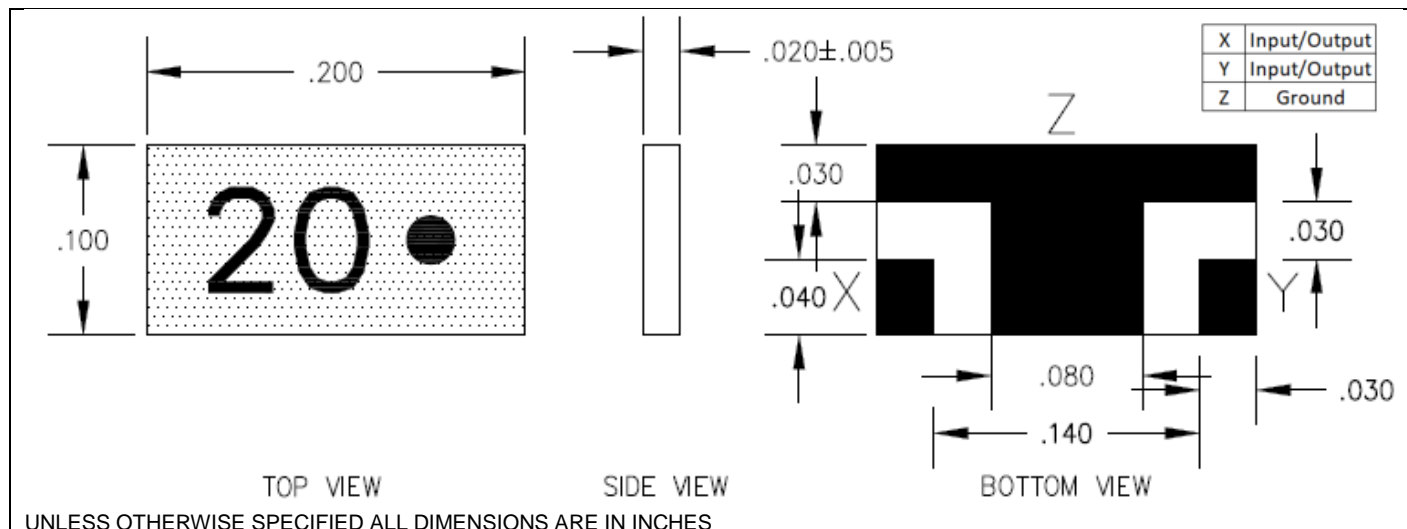
Tolerance is $\pm 0.010"$, unless otherwise specified. Designed to meet or exceed applicable portions of MIL-E-5400. **All dimensions in inches.**

Electrical Specifications

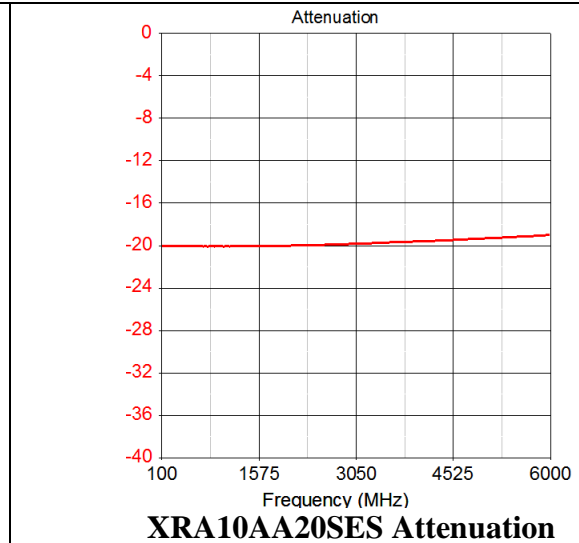
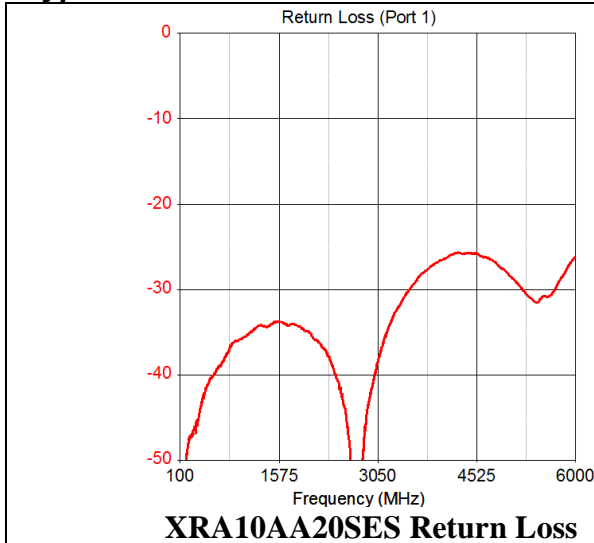
Attenuation Value:	20dB ± 1.0 dB
Power:	10 Watts
Frequency Range:	DC – 6.0GHz
Input Return Loss:	20dB DC - 5.0GHz 18dB 5.0 – 6.0GHz

Specification based on unit properly installed using suggested mounting instructions and a 50 ohm nominal impedance. **Specifications subject to change.**

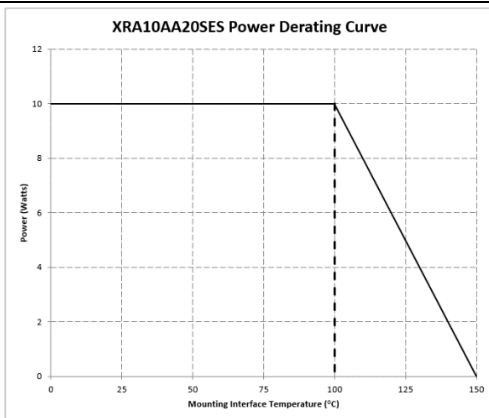
Outline Drawing



Typical Performance:

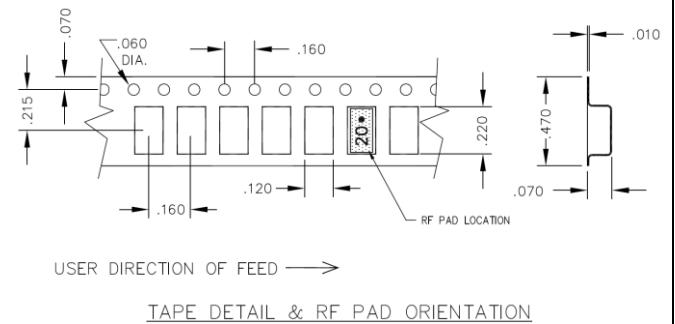


Power De-rating:

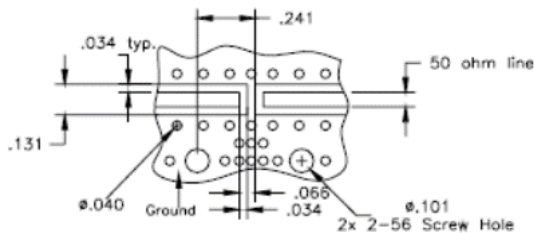


*Actual performance could be limited by the solder properties of the application

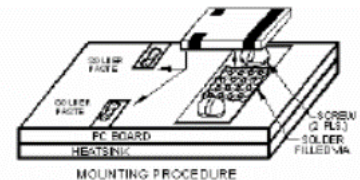
Tape and Reel:



Mounting Footprint:



Dimension given in inches.
For best thermal performance the PCB should be placed with thermal joint compound to the heat sink.



1. DRILL THERMAL VIAS THROUGH PCB AND FILL WITH SOLDER, SUCH AS S188.
2. SOLDER PART IN PLACE USING S188 TYPE SOLDER WITH A CONTROLLED TEMPERATURE IRON (250°C).
3. TO ENSURE GOOD THERMAL CONNECTIVITY TO HEAT SINK, DRILL AND TAP HEATSINK AND MOUNT PCB BOARD TO HEATSINK USING SCREWS.

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